

Power MOSFET 200 mAmps, 50 Volts N-Channel SC88

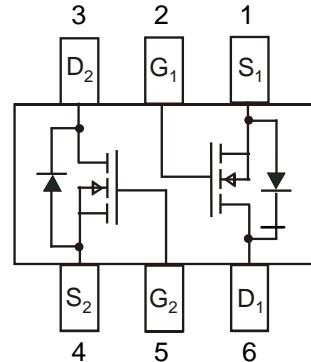
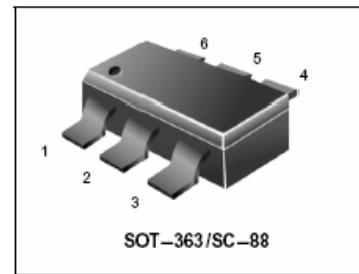
Typical applications are dc–dc converters, power management in portable and battery–powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low Threshold Voltage ($V_{GS(th)}$: 0.5V...1.5V) makes it ideal for low voltage applications
- Miniature SC88 Surface Mount Package saves board space
- Pb–Free Package May be Available. The G–Suffix Denotes a Pb–Free Lead Finish
- S–Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	50	Vdc
Gate-to-Source Voltage – Continuous	V _{GS}	± 20	Vdc
Drain Current – Continuous @ T _A = 25°C – Pulsed Drain Current (t _p ≤ 10 µs)	I _D I _{DM}	200 800	mA
Total Power Dissipation @ T _A = 25°C	P _D	380	mW
Operating and Storage Temperature Range	T _J , T _{stg}	– 55 to 150	°C
Thermal Resistance – Junction-to-Ambient	R _{θJA}	328	°C/W
Maximum Lead Temperature for Soldering Purposes, for 10 seconds	T _L	260	°C

**LBSS138DW1T1G
S-LBSS138DW1T1G**



ORDERING INFORMATION

Device	Marking	Shipping
LBSS138DW1T1G S-LBSS138DW1T1G	J1	3000 Tape & Reel
LBSS138DW1T1G S-LBSS138DW1T1G	J1	10000 Tape & Reel

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage ($V_{GS} = 0 \text{ Vdc}$, $I_D = 250 \mu\text{Adc}$)	$V_{(BR)DSS}$	50	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0 \text{ Vdc}$) ($V_{DS} = 50 \text{ Vdc}$, $V_{GS} = 0 \text{ Vdc}$)	I_{DSS}	— —	— —	0.1 0.5	μAdc
Gate-Source Leakage Current ($V_{GS} = \pm 20 \text{ Vdc}$, $V_{DS} = 0 \text{ Vdc}$)	I_{GSS}	—	—	± 0.1	μAdc

ON CHARACTERISTICS (Note 1.)

Gate-Source Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 1.0 \text{ mAadc}$)	$V_{GS(\text{th})}$	0.5	—	1.5	Vdc
Static Drain-to-Source On-Resistance ($V_{GS} = 2.75 \text{ Vdc}$, $I_D < 200 \text{ mAadc}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) ($V_{GS} = 5.0 \text{ Vdc}$, $I_D = 200 \text{ mAadc}$)	$r_{DS(\text{on})}$	— —	5.6 —	10 3.5	Ohms

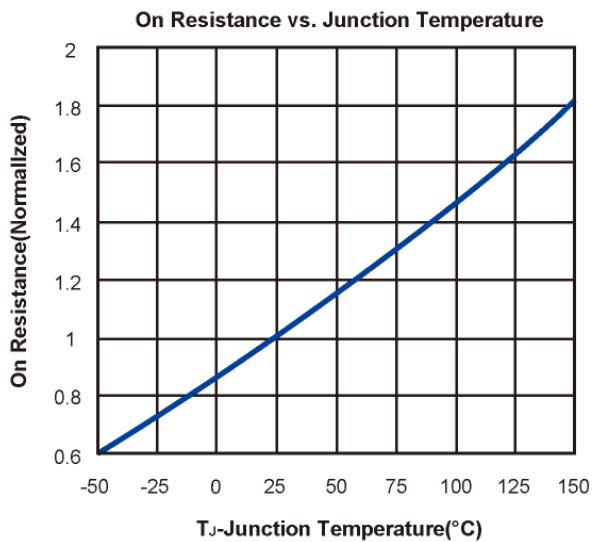
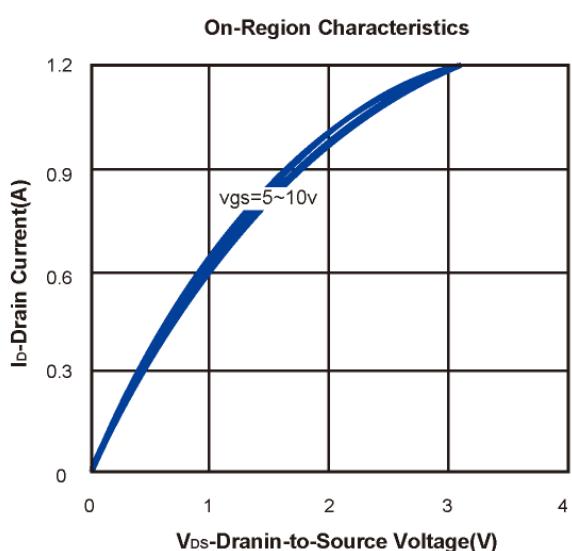
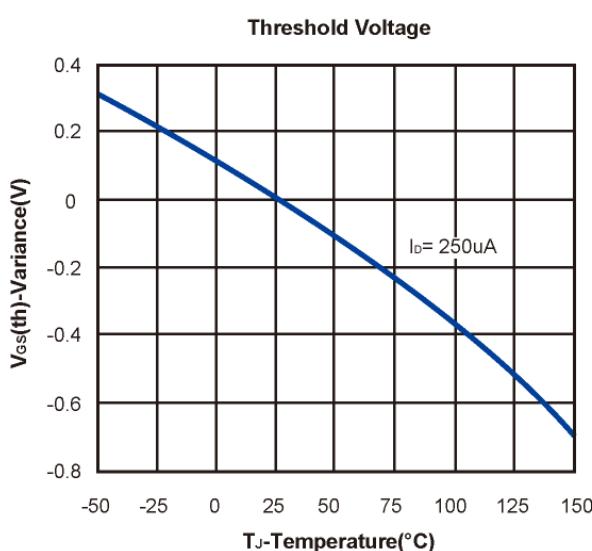
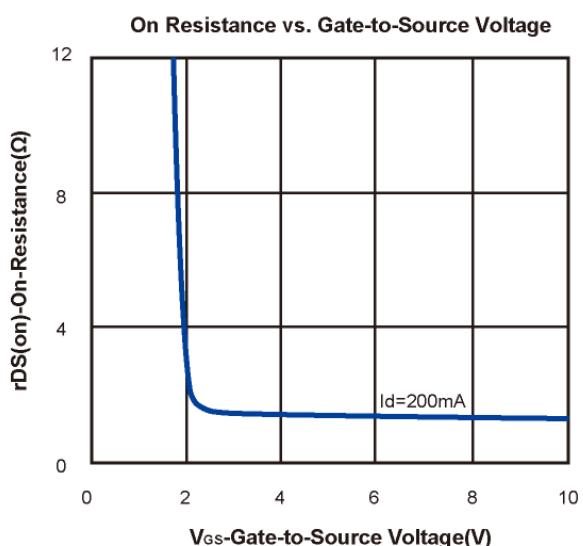
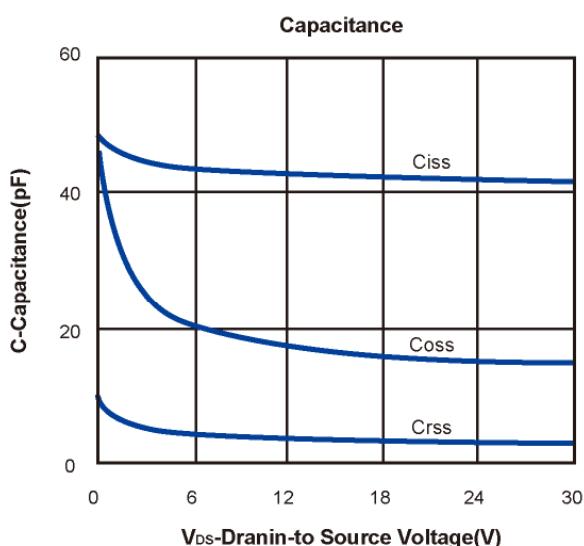
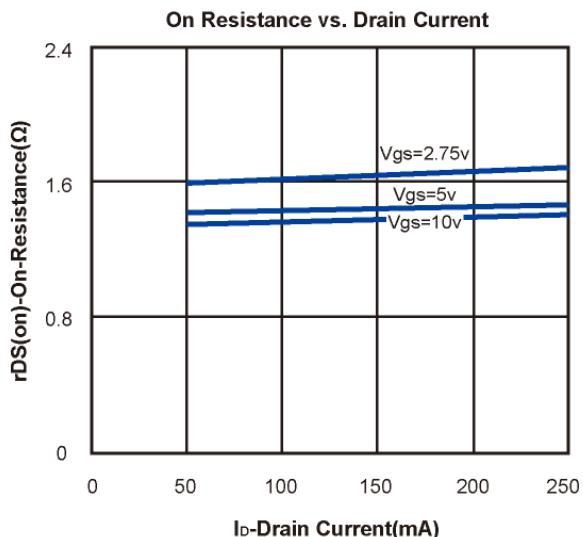
DYNAMIC CHARACTERISTICS

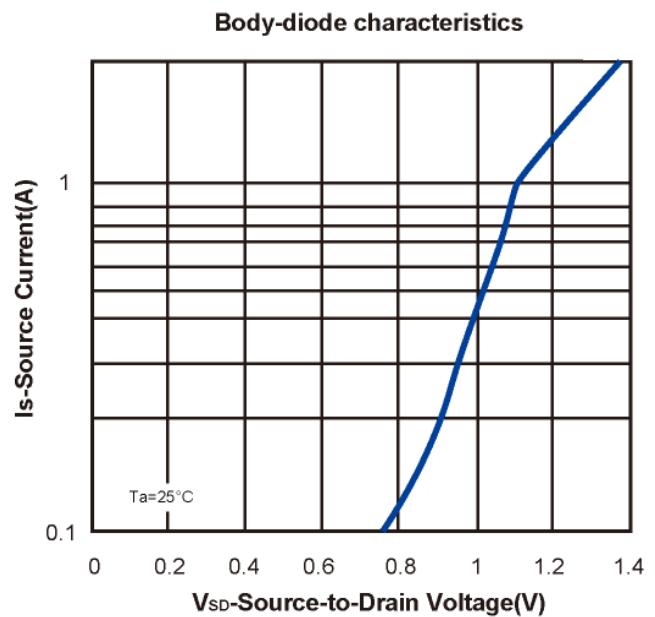
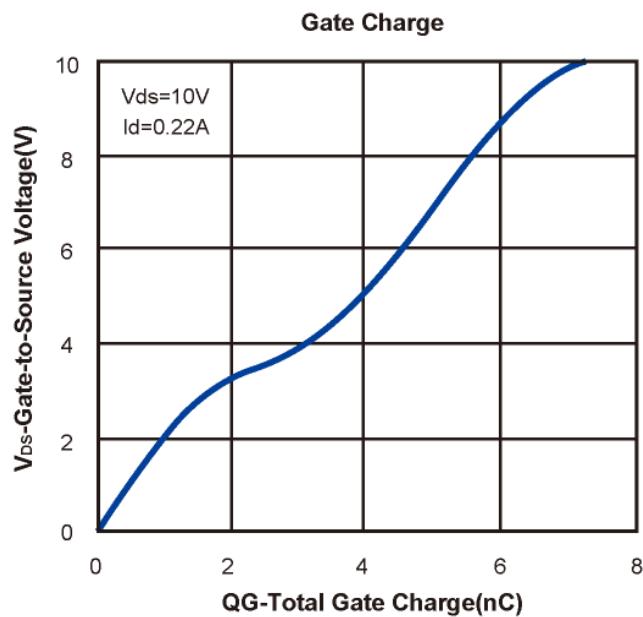
Input Capacitance	($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$)	C_{iss}	—	42	—	pF
Output Capacitance	($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$)	C_{oss}	—	15	—	
Transfer Capacitance	($V_{DG} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$)	C_{rss}	—	3	—	

SWITCHING CHARACTERISTICS (Note 2.)

Turn-On Delay Time	$(V_{DD} = 30 \text{ Vdc}$, $I_D = 0.2 \text{ Adc,}$)	$t_{d(on)}$	—	5	—	ns
Turn-Off Delay Time		$t_{d(off)}$	—	7	—	

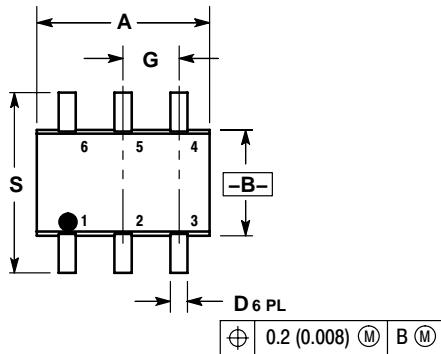
1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.
2. Switching characteristics are independent of operating junction temperature.

Typical Characteristics (TA=25°C Noted)

LBSS138DW1T1G , S-LBSS138DW1T1G


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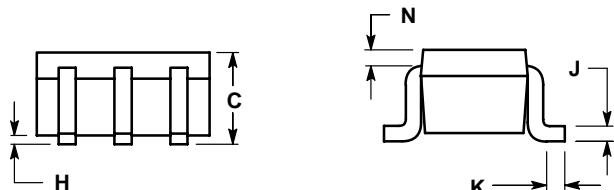
LBSS138DW1T1G , S-LBSS138DW1T1G

SC-88 (SOT-363)
CASE 419B-02
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20



STYLE 1:
PIN 1. Emitter 2
2. Base 2
3. Collector 1
4. Emitter 1
5. Base 1
6. Collector 2

SOLDERING FOOTPRINT*
